

N-Channel Super Junction Power MOSFET

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

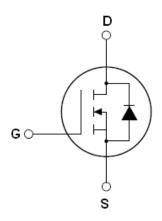
Features

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- Small package
- •Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

| V _{DS} | 700 | V |
|--------------------------|-----|----|
| R _{DS(ON)} TYP. | 165 | mΩ |
| I_D | 21 | A |



Schematic diagram

Package Marking And Ordering Information

| Device | Device Package | Marking |
|------------|----------------|------------|
| NCE70R180T | TO-247 | NCE70R180T |

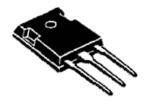


Table 1. Absolute Maximum Ratings (T_C=25℃)

| Parameter | Symbol | NCE70R180T | Unit |
|---|-------------------------|------------|------|
| Drain-Source Voltage (V _{GS} =0V) | V _{DS} | 700 | V |
| Gate-Source Voltage (VDS=0V) | V _{GS} | ±30 | V |
| Continuous Drain Current at Tc=25°C | I _{D (DC)} | 21 | Α |
| Continuous Drain Current at Tc=100°C | I _{D (DC)} | 13.2 | Α |
| Pulsed drain current (Note 1) | I _{DM (pluse)} | 63 | Α |
| Maximum Power Dissipation(Tc=25℃) | P_{D} | 200 | W |
| Derate above 25°C | | 1.6 | W/°C |
| Single pulse avalanche energy (Note 2) | Eas | 690 | mJ |
| Avalanche current ^(Note 1) | I _{AR} | 7 | Α |
| Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1) | E _{AR} | 1 | mJ |



| Parameter | Symbol | NCE70R180T | Unit |
|--|----------------|------------|------|
| Drain Source voltage slope, V _{DS} ≤480 V, | dv/dt | 50 | V/ns |
| Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_{D}$ | dv/dt | 15 | V/ns |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55+150 | °C |

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

| Parameter | Symbol | NCE70R180T | Unit |
|---|-------------------|------------|-------|
| Thermal Resistance, Junction-to-Case (Maximum) | R _{thJC} | 0.62 | °C /W |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R _{thJA} | 62.5 | °C /W |

Table 3. Electrical Characteristics (TA=25^oC unless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|--|---------------------|--|-----|------|------|------|
| On/off states | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | 700 | | | V |
| Zero Gate Voltage Drain Current(Tc=25℃) | I _{DSS} | V _{DS} =650V,V _{GS} =0V | | 0.05 | 1 | μA |
| Zero Gate Voltage Drain Current(Tc=125℃) | I _{DSS} | V _{DS} =650V,V _{GS} =0V | | | 100 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±30V,V _{DS} =0V | | | ±100 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250μA | 2.5 | 3 | 3.5 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =10.5A | | 165 | 190 | mΩ |
| Dynamic Characteristics | | | | | | |
| Forward Transconductance | g FS | V _{DS} = 20V, I _D = 10.5A | | 17.5 | | S |
| Input Capacitance | C _{lss} | \/ -50\/\/ -0\/ | | 1950 | | PF |
| Output Capacitance | Coss | V_{DS} =50V, V_{GS} =0V, F=1.0MHz | | 150 | | PF |
| Reverse Transfer Capacitance | C _{rss} | F=1.UIVID2 | | 5 | | PF |
| Total Gate Charge | Qg | \/ -400\/ -244 | | 45 | 70 | nC |
| Gate-Source Charge | Q _{gs} | V _{DS} =480V,I _D =21A, V _{GS} =10V | | 9 | | nC |
| Gate-Drain Charge | Q_{gd} | V _{GS} =10V | | 18 | | nC |
| Intrinsic gate resistance | R _G | f = 1 MHz open drain | | 1 | | Ω |
| Switching times | | | | | | |
| Turn-on Delay Time | t _{d(on)} | | | 11 | | nS |
| Turn-on Rise Time | t _r | V _{DD} =380V,I _D =11A, | | 6 | | nS |
| Turn-Off Delay Time | t _{d(off)} | $R_G=4\Omega, V_{GS}=10V$ | | 61 | 100 | nS |
| Turn-Off Fall Time | t _f | | | 4.5 | 12 | nS |
| Source- Drain Diode Characteristics | | | | | | |
| Source-drain current(Body Diode) | I _{SD} | T -25°C | | | 21 | Α |
| Pulsed Source-drain current(Body Diode) | I _{SDM} | T _C =25°C | | | 63 | Α |
| Forward on voltage | V _{SD} | Tj=25°C,I _{SD} =21A,V _{GS} =0V | | 0.9 | 1.3 | V |
| Reverse Recovery Time | t _{rr} | | | 310 | | nS |
| Reverse Recovery Charge | Q _{rr} | Tj=25°C,I _F =21A,di/dt=100A/μs | | 5 | | uC |
| Peak Reverse Recovery Current | I _{rrm} | | | 28 | | Α |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

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^{2.} Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

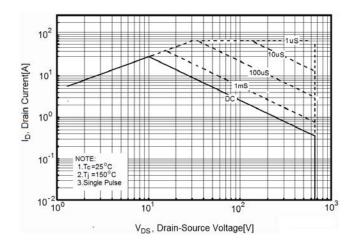


Figure 3. Source-Drain Diode Forward Voltage

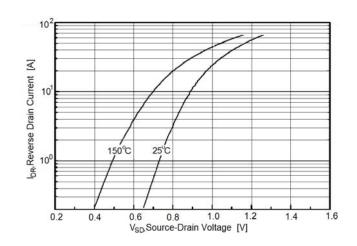


Figure 4. Output characteristics

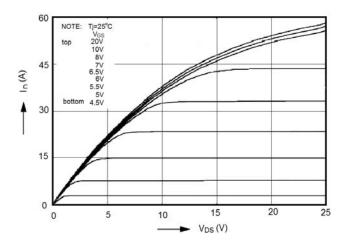


Figure5. Transfer characteristics

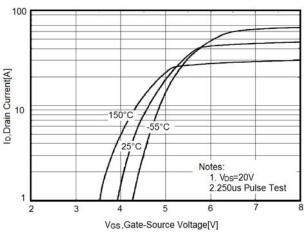
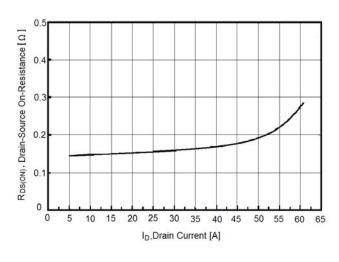


Figure 6. Static drain-source on resistance



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Figure 7. R_{DS(ON)} vs Junction Temperature

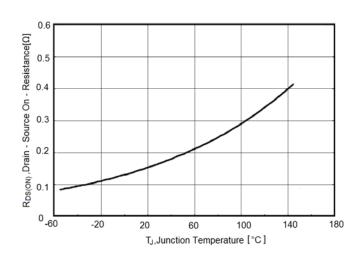




Figure8. BV_{DSS} vs Junction Temperature

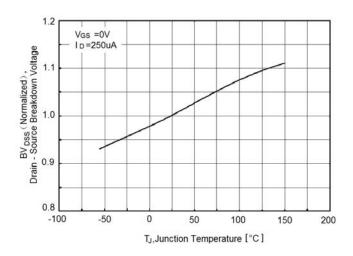


Figure 10. Gate charge waveforms

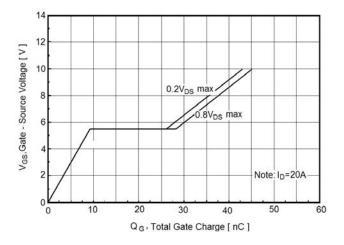


Figure 12. Transient Thermal Impedance

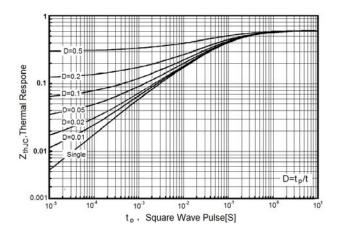


Figure 9. Maximum I_D vs Junction Temperature

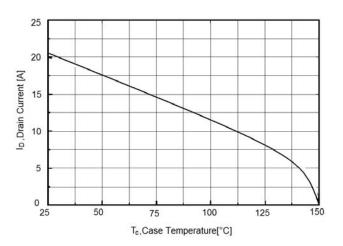
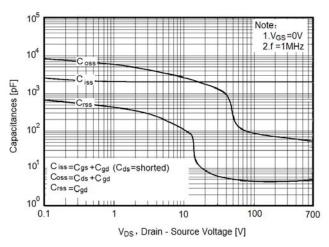


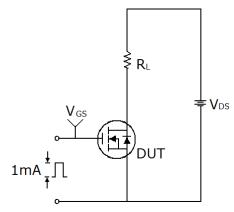
Figure11. Capacitance

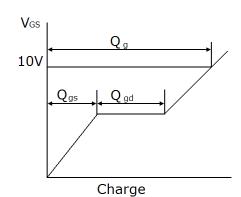




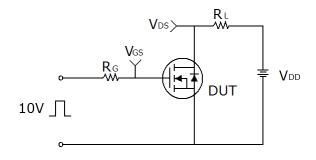
Test circuit

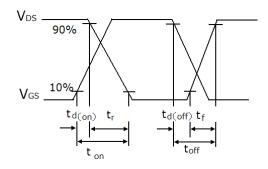
1) Gate charge test circuit & Waveform



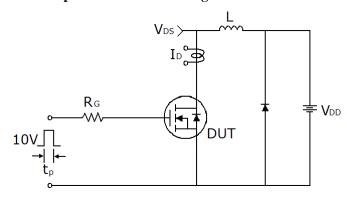


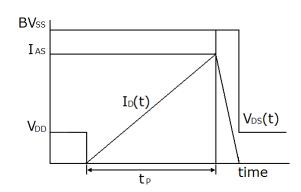
2) Switch Time Test Circuit:





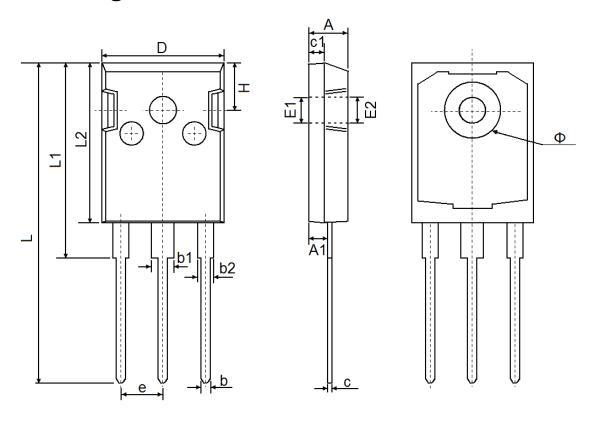
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-247 Package Information



| Complete | Dimensions | In Millimeters | Dimensions In Inches | | |
|----------|------------|----------------|----------------------|-------|--|
| Symbol | Min. | Max. | Min. | Max. | |
| Α | 4.850 | 5.150 | 0.191 | 0.200 | |
| A1 | 2.200 | 2.600 | 0.087 | 0.102 | |
| b | 1.000 | 1.400 | 0.039 | 0.055 | |
| b1 | 2.800 | 3.200 | 0.110 | 0.126 | |
| b2 | 1.800 | 2.200 | 0.071 | 0.087 | |
| С | 0.500 | 0.700 | 0.020 | 0.028 | |
| c1 | 1.900 | 2.100 | 0.075 | 0.083 | |
| D | 15.450 | 15.750 | 0.608 | 0.620 | |
| E1 | 3.500 | REF | 0.138 REF | | |
| E2 | 3.600 | 3.600 REF | | REF | |
| L | 40.900 | 41.300 | 1.610 | 1.626 | |
| L1 | 24.800 | 25.100 | 0.976 | 0.988 | |
| L2 | 20.300 | 20.600 | 0.799 | 0.811 | |
| Ф | 7.100 | 7.300 | 0.280 | 0.287 | |
| е | 5.450 | 5.450 TYP | | TYP | |
| Н | 5.980 REF | | 0.235 REF | | |



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